BIOGRAPHY

Advanced Packaging Summit 2025

Name: YunHyeok Im
Title/ Position: Senior Research Engineer
Company: Georgia Tech

Yunhyeok Im joined the Georgia Tech as a research faculty in Mechanical Engineering in 2023. As a member of CHIMES (Center for Heterogeneous Integration of Micro Electronic Systems) in JUMP 2.0 program, he is developing liquid cooling technology for 2.5D and 3D systems.
Before joining Georgia Tech, he had been with Samsung Electronics for 23 years. As a principal engineer, he impacted advanced thermal design decisions for SOC, ASIC, and Memory products in the early design stage. He published 29 technical papers and 54 United States (US) patents in Samsung. He earned his Ph.D in Mechanical Engineering from KAIST.

His current research interests include thermal architecture of advanced packages, fabrication of nanostructures for liquid cooling, finding new materials for enhanced heat transfer, and developing efficient simulation methodology.